L Number	Hits		DB	Time stamp
1	0	(led or (light adj emitting adj diode))	USPAT;	2003/08/05 14:33
		and (plated adj recess) and 257/\$.ccls.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	1
2	3	(led or (light adj emitting adj diode))	USPAT;	2003/08/05 14:15
		and (plated adj recess)	US-PGPUB;	2003/00/03 14.13
			EPO; JPO;	1
			DERWENT;	
			IBM TDB	
3	21	(plated adj recess) and 257/\$.ccls.	USPAT;	2002/00/05 14:22
		(P-100 da) 100000/ dild 25//\$:0015.		2003/08/05 14:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
4	2	(ellipsoidal adj dome) and 257/\$.ccls.	IBM_TDB	1 2002 (20 (25) 1) 5 5
	2	(ellipsoidal adj dome) and 25//\$.ccls.	USPAT;	2003/08/05 14:26
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
5	0	(elliptical add openantlant)	IBM_TDB	
Ĭ		(elliptical adj encapsulant) and 257/\$.ccls.	USPAT;	2003/08/05 14:24
		23774.0015.	US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
6	0	(allimonidal add announced)	IBM_TDB	
	U	(ellipsoidal adj encapsulant) and	USPAT;	2003/08/05 14:26
		257/\$.ccls.	US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
7	20	(lod on /light odd ominting of the	IBM_TDB	
′	20	the second secon	USPAT;	2003/08/05 14:58
		and (vias adj through adj substrate) and	US-PGPUB;	
		257/\$.ccls.	EPO; JPO;	
			DERWENT;	
8	87	(package) and (wine add there are	IBM_TDB	
	6 /	(package) and (vias adj through adj	USPAT;	2003/08/05 14:43
		substrate) and 257/\$.ccls.	US-PGPUB;	
			EPO; JPO;]
			DERWENT;	
9	4.0	/magle	IBM_TDB	
	40	(package) and (vias adj through adj	USPAT;	2003/08/05 14:43
		substrate) and recess	US-PGPUB;	
10			EPO; JPO;]
	[DERWENT;	
	300		IBM_TDB	
10	308	(led or (light adj emitting adj diode))	USPAT;	2003/08/05 14:59
	İ	and (package) and recess and 257/\$.ccls.	US-PGPUB;	
			EPO; JPO;	·
			DERWENT;	
			IBM TDB	

L Number	Hits		DB	Mima at
1	0	1 (ad) second ad IntelConnections)	USPAT;	Time stamp
		with (substrate adj surface) with led	US-PGPUB	2002/11/03 09:01
2	144	led with ((metallic or metal) adj layer)	1	2000/11/10
!		inclusive and the second secon	USPAT;	2002/11/03 10:09
3	0	encapsulant adj size adj substrate	US-PGPUB	
†	•	. The day substrate	USPAT;	2002/11/03 10:10
4	! 0	encapsulant adj length adj substrate	US-PGPUB	
•		substrate	USPAT;	2002/11/03 10:10
5	0	encapsulant with (length adj substrate)	US-PGPUB	
		substrate)	USPAT;	2002/11/03 10:10
6	1	encanculant with A in a	US-PGPUB	
	<u> </u>	encapsulant with (width adj substrate)	USPAT;	2002/11/03 10:10
_	0		US-PGPUB	
	U	("(semiconductor adj laser) and iiiv").PN.	USPAT;	2002/11/02 11:17
_			US-PGPUB	1 2002, 11, 02 11.1,
_	0	("(semiconductor adj laser) and (iii adj	USPAT;	2002/11/02 11:17
	_	(V)").PN.	US-PGPUB	2002/11/02 11:1/
_	0	("(semiconductor adj laser) and	USPAT;	2002/11/02 11:18
		gallium").PN.	US-PGPUB	2002/11/02 11:18
- [9	(semiconductor adj laser) and iiiv	USPAT;	2002/11/02 11 01
			US-PGPUB	2002/11/02 11:21
-	0	((semiconductor adj laser) and iiiv) and	1	2002/11/02 11
		(edge adj emitter)	USPAT;	2002/11/02 11:21
-	3	((semiconductor adj laser) and iiiv) and	US-PGPUB	
		edge	USPAT;	2002/11/02 13:30
-	1	6069440.pn.	US-PGPUB	
ĺ	_	555710.pm.	USPAT;	2002/11/02 13:30
_	. 1	6045240.pn.	US-PGPUB	
		0043240.pii.	USPAT;	2002/11/02 13:37
_	18		US-PGPUB	
	10	encapsulated adj light adj emitting adj	USPAT;	2002/11/02 13:41
_		diode	US-PGPUB	1 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2
	0	(encapsulated adj light adj emitting adj	USPAT;	2002/11/02 13:39
į		diode) with transparent	US-PGPUB	2002/11/02 13.39
-	0	(transparent adj encapsulated adj	USPAT;	2002/11/02 13:41
İ	ļ	material) adj substrate	US-PGPUB	2002/11/02 13:41
-	0	transparent adj encapsulated adj material	USPAT;	2002/11/02 12 12
	ĺ	i maccifut	1	2002/11/02 13:42
- }	87	transparent adj encapsulat\$	US-PGPUB	2002/11/22
		·	USPAT;	2002/11/02 13:43
-	17	(transparent adj encapsulat\$) and led	US-PGPUB	
		delicabantars) and ted	USPAT;	2002/11/03 08:58
			US-PGPUB	

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